



M T B F (E I A J R C R - 9 1 0 2 B)

					Model	SNDBS700B28
No.	P a r t s		Q' ty of Device	Failure rate [10 ⁻⁶ /H]	R e f e r e n c e	
1	IC	Linear	1	0.0240		
2	T r a n s i s t o r s	NPN/PNP	0	0.0000		
3	D i o d e s	FR	2	0.0440		
4	D i o d e s	switching	2	0.0150		
5	D i o d e s	Zener	0	0.0000		
6	Photoelectron Device	Photo-coupler	1	0.0700		
7	R e s i s t o r s	Metal Film	11	0.1760		
8	R e s i s t o r s	Carbon Film	4	0.0640		
9	R e s i s t o r s	Power Film	0	0.0000		
10	R e s i s t o r s	Temperature Fuse	0	0.0000		
11	R e s i s t o r s	variable	1	0.0160		
12	V a r i s t o r	Varistor	0	0.0000		
13	C a p a c i t o r s	Aluminum Electrolytic	4	0.0760		
14	C a p a c i t o r s	Film	8	0.0672		
15	C a p a c i t o r s	Ceramic	3	0.0780		
16	Coil	Line Filter	2	0.0009		
17	Coil	Ferrite Beads	2	0.0004		
18	Fuses		1	0.0200		
19	S w i t c h	Toggle	0	0.0000		
20	C o n n e c t o r s	Printed Crcuit Board	13	0.6760		
21	Connection	Hand Solder	21	0.0546		
22	Connection	Flow Solder	378	0.1966		
23	Connection	Screw	15	0.0150		
24	Printed Crcuit Board	Through Hole	1	0.0450		
25	P S 1		1	3.8738		
Total Failure Rate [10 ⁻⁶ /H]				5.5125		

M T B F	[H]	181,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-